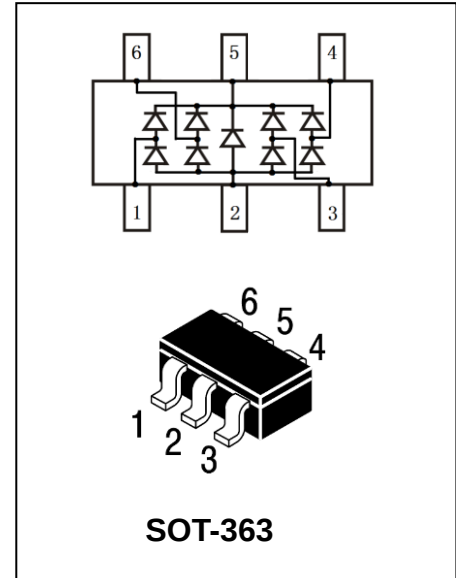


Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects four I/O lines
- ◆ Low capacitance ($<1pF$) for high-speed interfaces
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

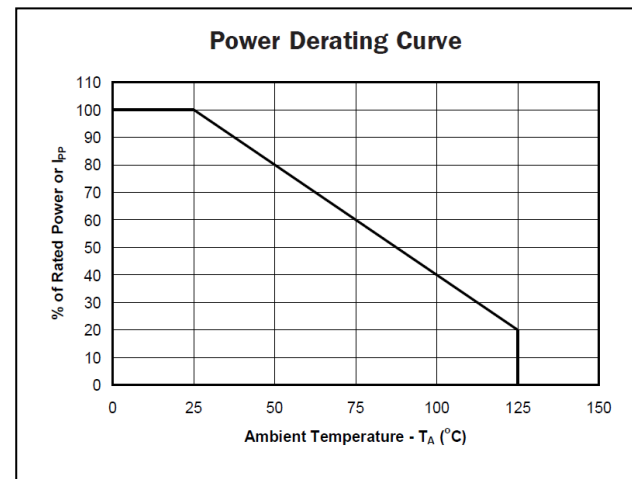
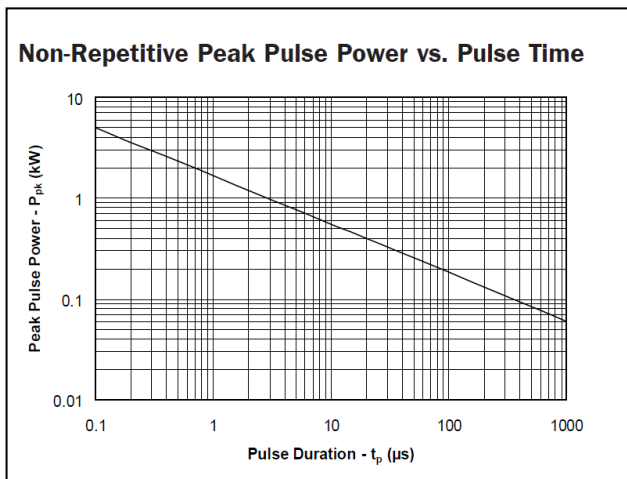
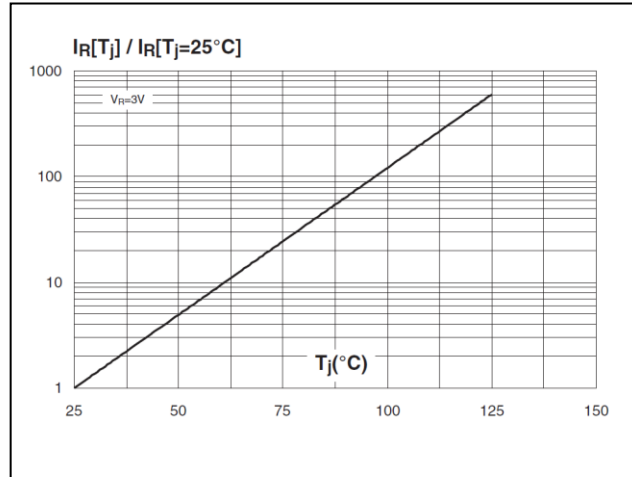
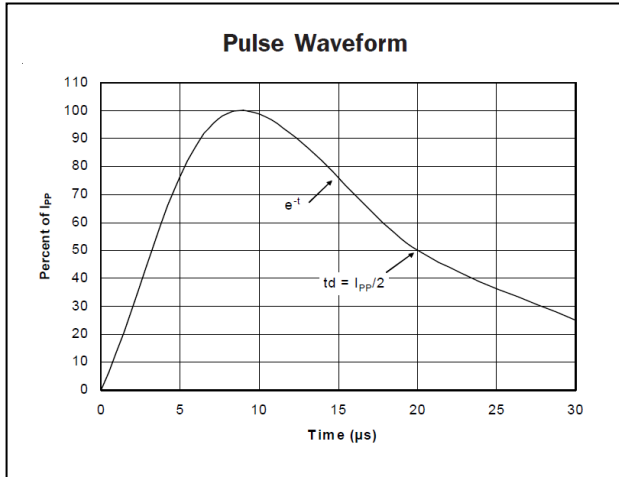
Maximum Rating @ $T_a=25^\circ C$ unless otherwise specified

Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	150	Watts
T_L	Lead Soldering Temperature	260(10sec.)	$^\circ C$
T_J	Operating Temperature	-55 to +125	$^\circ C$
T_{STG}	Storage Temperature	-55 to +150	$^\circ C$

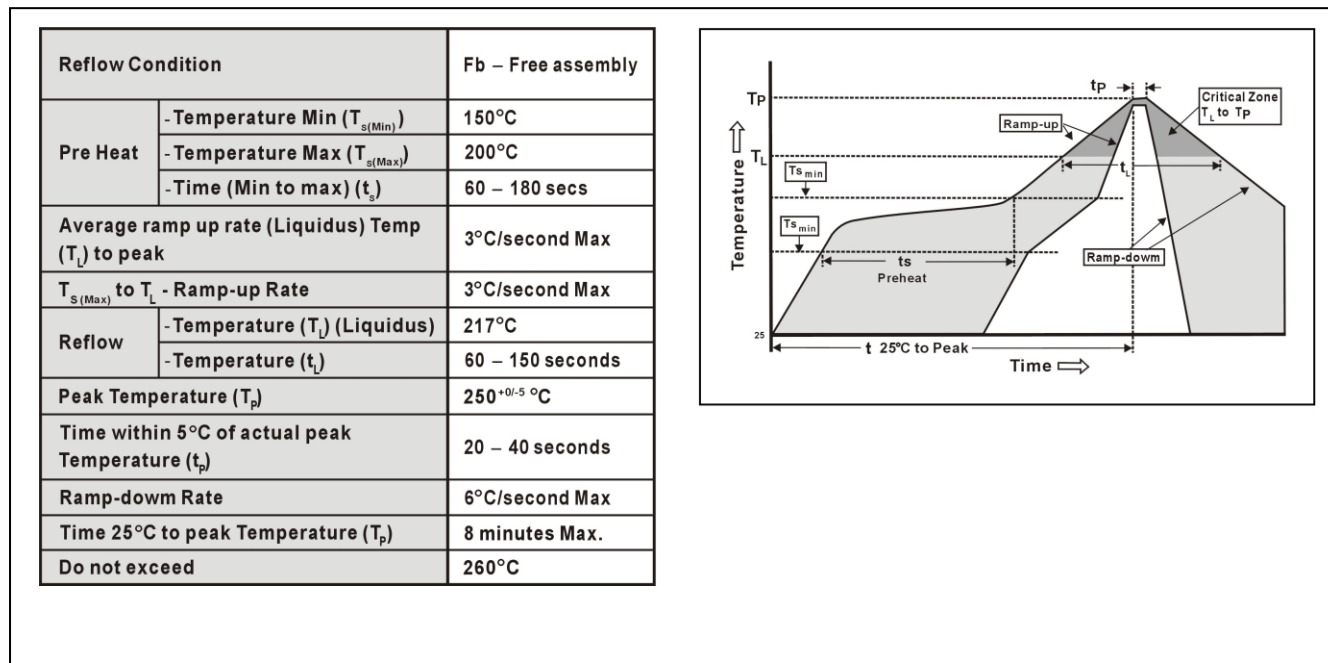
Electrical Characteristics@ Ta=25°C unless otherwise

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{RWM}	Reverse Working Voltage	Any I/O to Ground			5.0	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1mA$, Any I/O to Ground	6.0			V
I_R	Reverse Leakage Current	$V_{RWM} = 5V$, Any I/O to Ground			1	μA
V_C	Clamping Voltage	$I_{PP} = 1A$, $t_p = 8/20\mu s$, any I/O pin to Ground			10	V
		$I_{PP} = 3A$, $t_p = 8/20\mu s$, any I/O pin to Ground			15	V
C_J	Junction Capacitance	$V_R = 0V$, $f = 1MHz$, between I/O pins		0.3	0.5	pF
		$V_R = 0V$, $f = 1MHz$, any I/O pin to Ground		0.6	0.8	pF

Typical Characteristics@ $T_a=25^{\circ}\text{C}$ unless otherwise specified



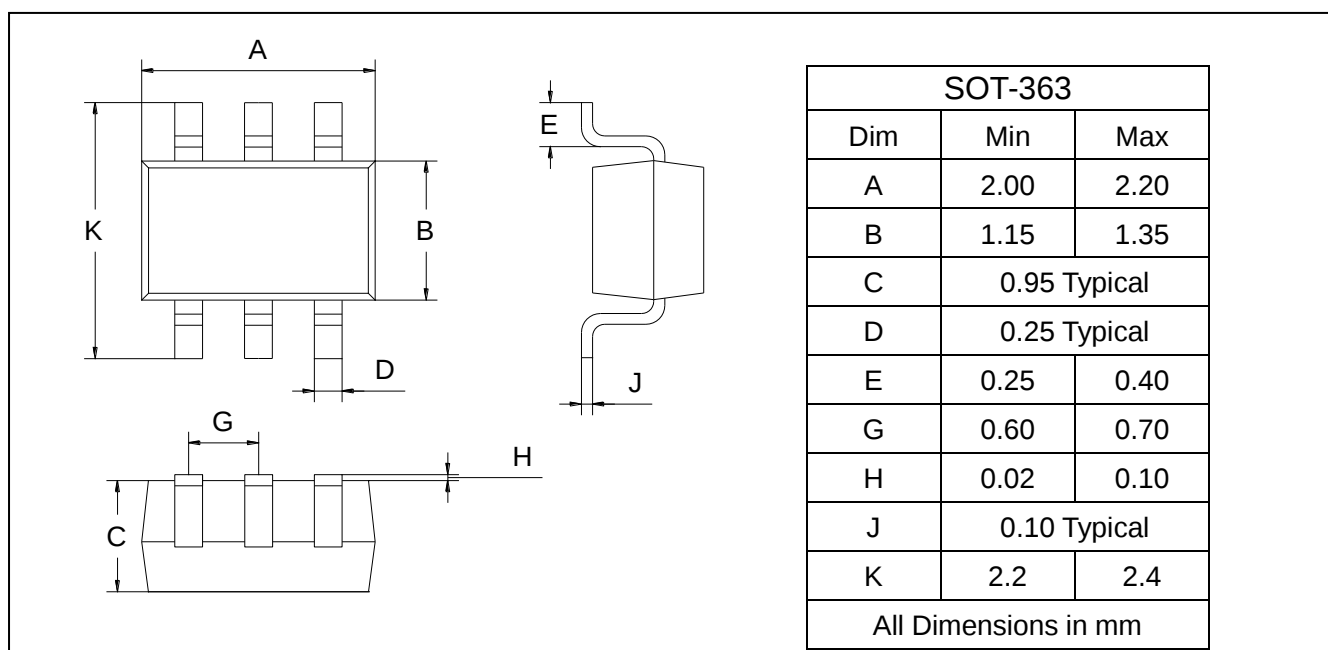
Soldering Parameters



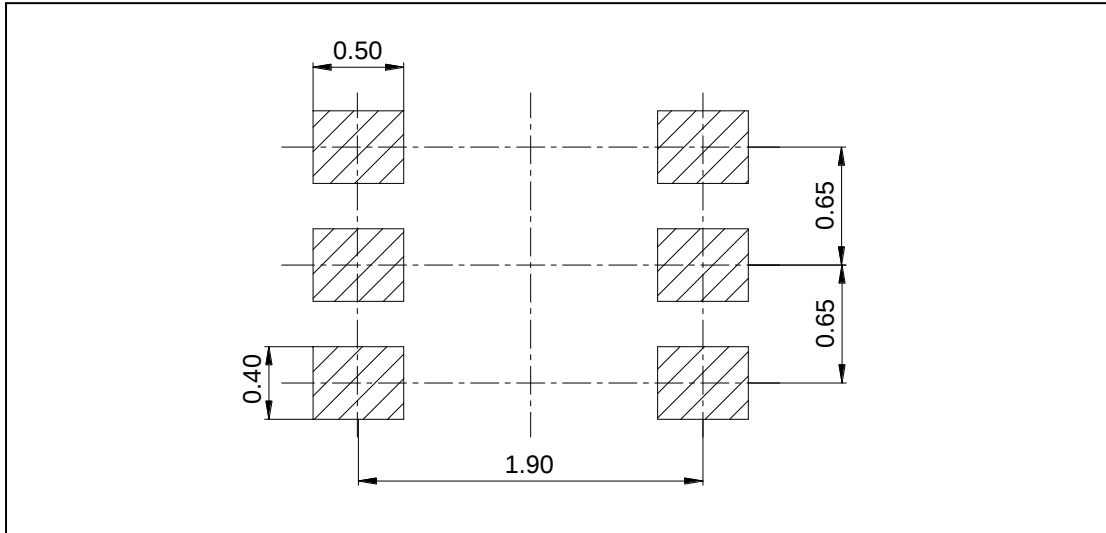
Package Outline

Plastic surface mounted package

SOT-363



Soldering Footprint



Package And Marking Information

Device	Package	Shipping	Reel Size
ZX0504F	SOT-363	3000/Reel	7 inch